

Re Amended  
10/1/02

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: **Nirio FUKUSAWA et al.**

PATENT APPLICATION

Serial Number: **(Divisional of Appln. Serial No.  
09/029,608, filed March 15, 1998)**

Prior Art Unit: 2814

Filed: Herewith

Prior Examiner: **D. Graybill**

For: **METHOD AND MOLD FOR MANUFACTURING SEMICONDUCTOR  
DEVICE, SEMICONDUCTOR DEVICE, AND METHOD FOR MOUNTING  
THE DEVICE**

PRELIMINARY AMENDMENT

Director of Patents and Trademarks  
Washington, D.C. 20231

Date: January 23, 2001

Sir:

Prior to examination, please amend the above-identified application as follows:

IN THE CLAIMS:

Please cancel claims 1-86 without prejudice or disclaimer and add new claims 87-97 as follows:

add B1

--87 A semiconductor device comprising:

a semiconductor element having a surface on which protruding electrodes are formed, the protruding electrodes having a straight shape on a lateral surface thereof;

a conductive film covering a top surface of the protruding electrodes; and

a resin layer which is formed on the surface of the semiconductor element and seals at least the lateral surface of the protruding electrodes.